

# **NEMI Materials Declaration Team Phase 2**

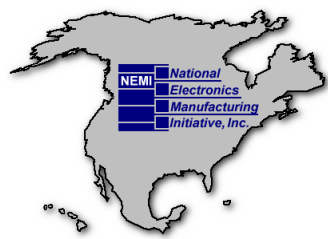
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**Dr. Nancy Bolinger, IBM, Project Chair**

**Diane Fisher, HP, Project Co-Chair**

**NEMI RoHS / WEEE Summit, Louisville, Colorado**

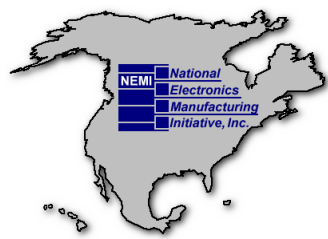
**October 19, 2004**



# Team Acknowledgement

- **A. Priebe, Centor**
- **Alan Ater, Sanmina-SCI**
- **Allan Dobney, Cisco**
- **Andrew Wertkin, Synapsis**
- **Barry Gross, Plexus**
- **Bert Honour**
- **Bert Lange, Texas Instruments**
- **Bill Witt, The Goodbye Chain**
- **Brian Toleno, Loctite**
- **Bruce Schultz, JCI**
- **Carl B Schultz, Tyco Electronics**
- **Carlos Vazquez, Motorola**
- **Carol Ann McDevitt, Cisco**
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- **Danny Salinas, Nortel Networks**
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- **Diane Fisher, HP, Project Co-Chair**
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- **Jerome Wagner, Eitny**
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- **Jerry Gleason, HP**
- **Jessica Mayes**
- **Joey Campbell, Kemet**
- **Jun Yamaguchi, Fuji Film**
- **Kara Thompson, Dell**

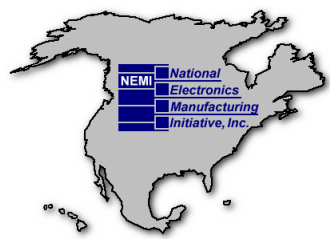
*Connect with and Strengthen your Supply Chain*



# Team Acknowledgement

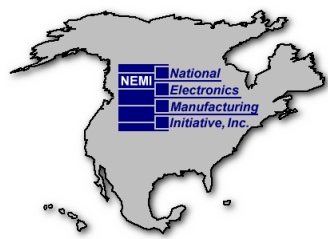
- Keith Gray, EMT
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- Laura Przekop, URS
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- M Clark, Centor
- Marissa Yao, Intel
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- Thomas A Martin
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- Todd A Brady, Intel
- Todd Okrasinski, Lucent
- Vinay Goyal, Logic

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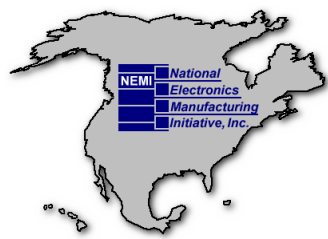
# Overview

- **Materials Declaration Phase 2 Project**
  - **Materials Declaration Format**
  - **Materials Declaration Process**
  - **RoHS and WEEE Overview Education**
- **Open Issues**
- **Summary**



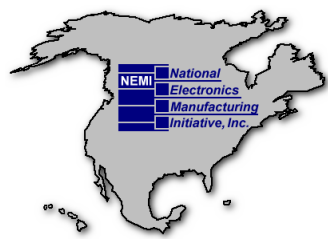
# Materials Declaration Phase 2 Project

- **Objectives:**
  - Recommend a common materials declaration format and process for industry that can be automated and used across the supply chain
  - Leveraged from the
    - Joint Industry Guide
    - IEC 61906 (DIN 19220)
    - ISO/IEC Guides 22 and 17050
    - ERA Technology Possible Compliance Approaches for RoHS
    - WEEE Directive
  - Minimize supply chain cost impact
  - Simplify data collection for requesters and data reporting for suppliers
  - Expandable to support multiple declaration levels
- **Deliverables**
  - Recommend materials declaration format and process
  - RoHS and WEEE overview education
- **Website:** [www.nemi.org/projects/ese/Materials\\_Declarations.html](http://www.nemi.org/projects/ese/Materials_Declarations.html)



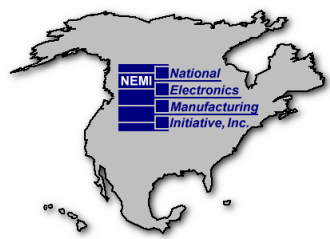
## Phase 2 Project Schedule

- **Launched Phase 2 project** **May 2004**
  - **Guide, Tools and Standards reviewed**
    - **Draft Joint Industry Guide (baseline)**
    - **Compliance Connect**
    - **RosettaNet (PIP 2A10 and 2A13)**
    - **PDX 2.0**
    - **JGPSSI**
    - **IPC, SAP EHS, ISO/IEC**
  
- **Draft format and process developed** **May-October**
  
- **Present format /process at NEMI summit** **October 2004**
  
- **Complete phase 2 project, issue report** **December 2004**



# Materials Declaration Format

- **Format (see Excel file)**
  - **JIG (baseline), Compliance connect, RosettaNet (PIP 2A10, 2A13) PDX 2.0, JGPSSI**
  
  - **Harmonizing requirements into set of mandatory and optional data fields**
  
  - **Expandable for multiple levels of declaration**
    - Self-declaration, minimum legal reporting, full disclosure
    - Bulk material, component, sub-assembly, and product level reporting
    - Query and response (customer -> supplier -> customer) and publish (supplier -> customer) data exchange processes
    - Multi-tier supply chain data collection
    - “Electronic signature” of supplier provided data to support liability requirements
  
  - **Capabilities and Recommendations**
    - **Multi-level assembly**
    - **Concentration per unit capability**
    - **Absence declaration**
    - **Standardization of common substance codes**
    - **Standardization of property values**
    - **Expandable for different levels of declaration**
    - **Full vs Partial disclosure**
    - **Interchange format**

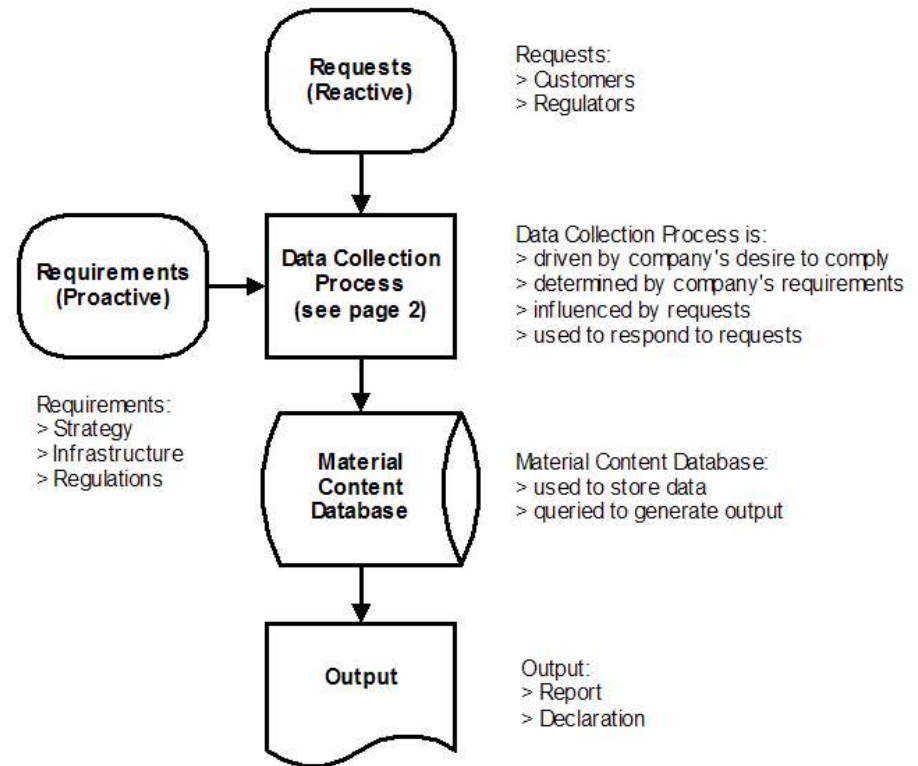


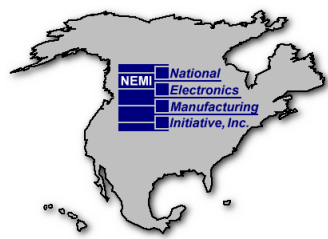
# Materials Declaration Process

**Process Sub-Team Leader:  
JB Hollister**

- **Four-stage Process**

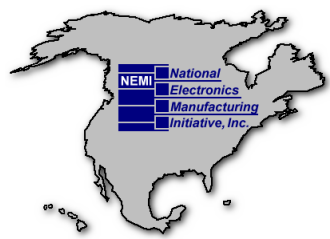
- **Ask**
- **Analyze**
- **Act**
- **Accept**





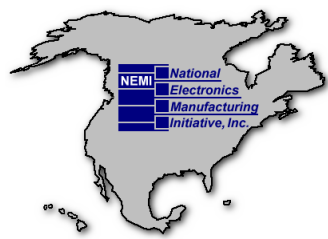
# RoHS and WEEE Overview Education

- **Supply Chain Communication**
  - **RoHS Overview Education**
    - Jim Dills, The GoodBye Chain Group
    - <ftp://nemi.org/webdownload/projects/ese/Supplier%20Education.pdf>
    - Overview of RoHS-WEEE Supplier Education
  
    - Chris Harden, MDSMap<sup>SM</sup>
    - [ftp://nemi.org/webdownload/projects/ese/RoHS\\_overview\\_MDSMap.pdf](ftp://nemi.org/webdownload/projects/ese/RoHS_overview_MDSMap.pdf)
    - Overview of the European Union's RoHS Directive
  - **WEEE Overview Education**
    - Orlean Thompson, Eastman Kodak
    - [ftp://nemi.org/webdownload/projects/ese/WEEE\\_Directive.pdf](ftp://nemi.org/webdownload/projects/ese/WEEE_Directive.pdf)
    - WEEE Directive



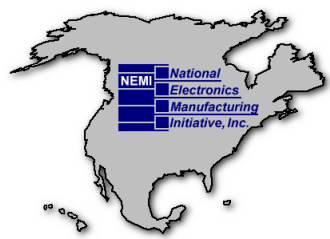
# For Discussion

- **Who determines compliance?**
  - **Assembly, manufacturing process capability, information**
  - **PN vs subassembly reporting: aggregation**
  - **Absence Declaration**
  - **Exemptions: Inherit vs End product**
    - **Server, Telecommunications equipment**
  - **Mechanism for Expandability**
    - **XML Schema Elements**
    - **Generic Dictionary Term**
  - **Per unit of measure**
    - **Cr+6 per surface area of sheet metal**
    - **Pb per length of wire**
- Connect with and Strengthen your Supply Chain*



# Summary

- **Next steps:**
- **Recommend process for materials declaration data collection, analysis and reporting with support for:**
  - **Self-declaration, minimum legal reporting, full disclosure**
  - **Multi-tier supply chain data collection**
  - **“Electronic signature” of supplier provided data to support liability requirements**
  - **B2B infrastructure required to support the above**
    - **Support for “low-tech” data exchange (i.e., e-mail, spreadsheet) and integration into “high-tech” (i.e., XML-based)**



**Thank you.**

*Connect with and Strengthen your Supply Chain*